

Silicon Tracking In Mokka

Valeri Saveliev (Obninsk State Uni)
on behalf SiLC Collaboration



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Implementation

- ➤ SIT: 2 barrel layers of Si thickness 275 microns + Carbon Fiber Support thickness 1mm
- FTD: Seven Disks

 First 3 disks (pixel technology) Si thickness 50 microns +

 Carbon Fiber support thickness 1 mm,

 Last 4 disks (strip technology) Si thickness 275 microns +

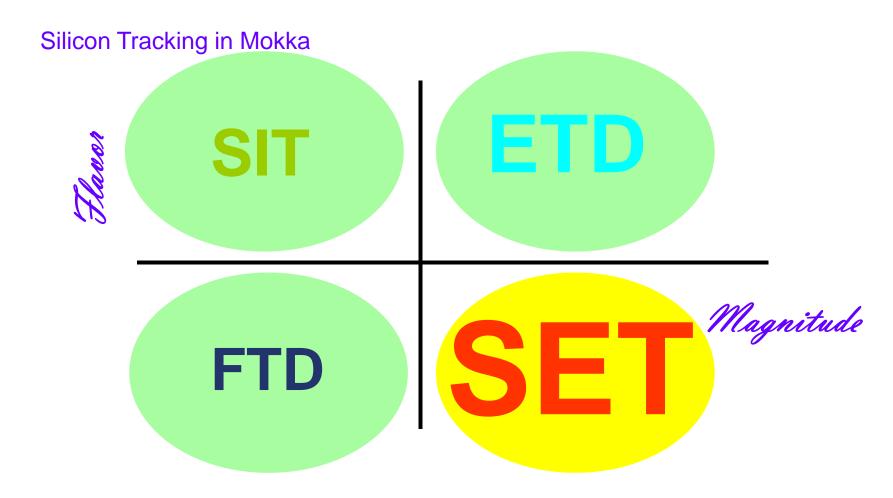
 Carbon Fiber Support 1 mm,
- ➤ ETD 3 disks, XUV plane (strip technology) Si thickness 275 microns + Carbon Fibers Support 1 mm,
- ➤ SET 2 barrel layers of Si, thickness 275 microns + Carbon Fiber Support 1 mm,

Material Budget of one layer 275 microns of Si + 1mm of Carbon is 0.65%





Main Si Tracking components





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Implementation

- > Drivers: SIT, FTD, ETD, SET is ready and implemented in Mokka
- > Super Drivers:

SSit02, SFtd02, Setd01 is implemented and included in the Detector Model LDC01_06Sc_test SSet01 is implemented, needed to include in the Detector Model

- Super Drivers SSit02, SFtd02, Setd01 are tested with Detector Model LDC01_06Sc_test,
- ➤ Sharing parameters table is modified for using the SiLC superdrivers with connection mainly to TPC and ECal parameters.

